

### Water Erosion Resistant Surface Treatments Using Laser Peening and Low Plasticity Burnishing

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# Outline

- LPB Process
- DOE Analysis for LPB
- Residual Stress Measurement
- Water Erosion Rig Test
- Future Work

## Low Plasticity Burnishing



Ecoroll Burnishing Equipment

# Low Plasticity Burnishing

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a) LPB Process



b) LPBTool

# Low Plasticity Burnishing



a) Ti64 disk before LPB b) Ti64 disk after LPB

## Cutting Pattern of LPB Disk



D=3.1 inch T= 0.625 inch

# Modeling of LPB Process





#### Pressure: 200Bar Feed: 1mm/sec





#### Progress of Residual Stresses during LPB





### **Plastic Strain**



### LPB modeling from Literature







#### Preliminary Modeling of LPB process





#### Preliminary Modeling of LPB process







# DOE for LPB



2-level Full factorial design: 16 runs of experiments Analysing Software: Minitab



Surface roughness of the substrate: Ra = 0.326 micrometer





Ra: Arithmetical Mean Roughness

A: Spindle Velocity B: Feed

- C: No. of Passes
- D: Pressure <sup>18</sup>



Estimated	Effects	and Coefficients	for	Ra	(coded	units)
Term	Effect	Coef				
Constant		0.11456				
A	-0.00587	-0.00294				
В	0.07237	0.03619				
С	-0.01038	-0.00519				
D	-0.02063	-0.01031				
A*B	-0.02262	-0.01131				
A*C	0.00862	0.00431				
A*D	0.01238	0.00619				
B*C	0.00487	0.00244				
B*D	0.00612	0.00306				
C*D	0.00688	0.00344				
A*B*C	0.00987	0.00494				
A*B*D	0.01112	0.00556				
A*C*D	-0.01013	-0.00506				
B*C*D	0.00362	0.00181				
A*B*C*D	-0.01138	-0.00569				

**Conclusion**: In order to have a much smoother surface, it's better to set the feed at the low level.





Surface hardness of the substrate: 300.317HV



Microhardness of Substrate Ti64



Vickers Hardness Parameters: Load: 50g; Time: 15s

A: Spindle Velocity B: Feed C: No. of Passes D: Pressure







#### **Residual Stress Measurement**

#### **Incremental Center Hole-Drilling Method**

- Combined with Strain Gage
- Combined with Digital Image Correlation

#### Hole-Drilling Strain Gage Method





#### Hole-Drilling Strain Gage Method



$$\varepsilon = \frac{\Delta R/R}{K}$$

Where:

 $\Delta R = R_{\rm f} - R_{\rm i}$  (Ohm) for each drilling increment;

 $R_{i}$  is the reading of the resistance strain gage before the first drilling increment;

 $R_{t}$  is the reading of resistance strain gages for each drilling increment.

#### Incremental hole-drilling combined with DIC





Schematic arrangement used for 2-D Digital Image Correlation (from Sutton et al.)

NPL, in partnership with Airbus, AWE, Stresscraft,British Energy and LA Vision has demonstrated the world's first application of using DIC for the measurement of residual stress with the incremental hole drilling technique.

#### Incremental hole-drilling combined with DIC

Before drilling

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#### After drilling



#### Features of Strain Gauge and Optical Measurements

	Strain Gauge Measurements		Optical Measurements		
•	Moderate equipment cost, high per-measurement cost	٠	High equipment cost, moderate per-measurement cost		
<ul> <li>Significant preparation and measurement time</li> </ul>		•	<ul> <li>Preparation and measurement time can be short</li> </ul>		
٠	Small number of very accurate and reliable measurements	•	Large number of moderately accurate and reliable measurements		
•	Stress calculations are relatively compact	•	Stress calculations can get quite large		
٠	<ul> <li>Modest capabilities for data averaging and self-consistency checking</li> </ul>		Extensive capabilities for data averaging and self-consistency checking		
٠	Relatively rugged, suitable for field use	٠	Delicate, more suited to lab use		
•	Sensitive to hole-eccentricity errors	•	Hole eccentricity can be corrected		

#### **Incremental Center Hole-Drilling Method**

#### • Challenges:

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High speed(up to 400000rpm) drilling should be used for Ti64 alloy.

Strain gage measurement result is sensitive to holeeccentricity errors.

The testing specimen should not be moved from the camera during the hole-drilling DIC process.

#### Incremental Center Hole-Drilling Euipment



Vishay Company

# Water Erosion Rig Test

#### **Progress:**

- Set up preliminary test with 400µm nozzle(3 orifices and 1 orifice).
- Investigated the effect of the rig parameters.
- Constructed the preliminary LIE stage curve of the substrate Ti64.
- LIE surface and erosion mechanism study.

#### Water Erosion Rig Test(3 orifices)

Preliminary LIE stage curve of substrate Ti64(400µm nozzle)



### Water Erosion Rig Test (1 orifice)

Pressure: 20psi Flow rate: 0.02~0.03L/min Nozzle size: 400µm Droplet size: 497µm Distance between the nozzle and the sample: 50mm



The purpose of this test: To investigate the effect of different placement of the nozzle(by rotating the nozzle with one side orifice open 180 degree) to the erosion pattern.

## LIE Surface SEM Study





### LIE Mechanism



50.0um TMG 15.0kV 10.5mm x1.50k SE

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30.0um



### LIE Mechanism



### Future Work...

- Cutting the LPB disks into T-shaped samples(water jet cutting).
- Residual stress measurements for LPB samples.
- Based on the analysis done by DOE(Minitab), get the optimized parameters.
- Confirm the results done by DOE with experimental work.

